What is claimed is:

1. A function module comprising:

a first circuit board including a first surface with a first ground layer formed thereon;

a second circuit board, coupled to the first circuit board, including a second surface facing the first surface, wherein a second ground layer is formed on the second surface; and

a heat dissipation fin, disposed between the first circuit board and the second circuit board, abutting the first ground layer and the second ground layer respectively.

2. The function module as claimed in claim 1, wherein the first circuit board further includes a third surface, opposite to the first surface, with a first device located thereon.

3. The function module as claimed in claim 1, wherein the second circuit board further includes a fourth surface, opposite to the second surface, with a second device located thereon.

4. The function module as claimed in claim 1, wherein both the first ground layer and the second ground layer are made of copper.

5. The function module as claimed in claim 1, wherein both the thickness of the first ground layer and the thickness of the second ground layer are substantially not less than 1.5 mil.

6. The function module as claimed in claim 1, further comprising a flat cable connecting the first circuit board and the second circuit board, providing communicability therebetween.

7. The function module as claimed in claim 1, further comprising a connector connecting the first circuit board and the second circuit board, providing communicability therebetween.

8. The function module as claimed in claim 7, wherein the connector is a slot connector.

9. The function module as claimed in claim 1, further comprising:

a first heat spreader, disposed between the heat dissipation fin and the first ground layer, for uniformly spreading the heat over the first circuit board; and

a second heat spreader, disposed between the heat dissipation fin and the second ground layer, for uniformly spreading the heat over the second circuit board.

10. The function module as claimed in claim 9, wherein both the first heat spreader and the second heat spreader are made of copper, aluminum, metallic composite material, or non-metallic composite material.

11. The function module as claimed in claim 9, wherein both the thermal conductivity of the first heat

spreader and the thermal conductivity of the second heat spreader are not substantially, less than 100W/m• K.

12. The function module as claimed in claim 1, further comprising:

a first adhesion layer, disposed between the heat dissipation fin and the first ground layer, for combining the heat dissipation fin with the first circuit board; and

a second adhesion layer, disposed between the heat dissipation fin and the second ground layer, for combining the heat dissipation fin with the second circuit board.

13. The function module as claimed in claim 12, wherein both the first adhesion layer and the second adhesion layer comprise one selected from the group consisting of brazing solder, tin solder, thermal interface material, grease and the combination thereof respectively.

14. The function module as claimed in claim 1, further comprising a fan, connected to the heat dissipation fin, for dissipating heat therefrom.

15. A function module comprising:

a first circuit board including a first surface with a first heat conduction layer formed thereon;

a second circuit board, coupled to the first circuit board, including a second surface facing the first surface, wherein a second heat conduction layer is formed on the second surface; and

a heat dissipation fin disposed between the first circuit board and the second circuit board, abutting the first heat conduction layer and the second heat conduction layer respectively.

16. The function module as claimed in claim 15, wherein the first heat conduction layer is a ground layer of the first circuit board, and the second heat conduction layer is a ground layer of the second circuit board.

17. The function module as claimed in claim 15, wherein the first circuit board further includes a third surface, opposite to the first surface, with a first device located thereon.

18. The function module as claimed in claim 15, wherein the second circuit board further includes a fourth surface, opposite to the second surface, with a second device located thereon.

19. The function module as claimed in claim 15, wherein both the first heat conduction layer and the heat conduction layer are made of copper.

20. The function module as claimed in claim 15, wherein both the thickness of the first heat conduction layer and the thickness of the second heat conduction layer are not substantially less than 1.5 mil.

21. The function module as claimed in claim 15, further comprising a flat cable connecting the first

circuit board and the second circuit board, providing communicability therebetween.

22. The function module as claimed in claim 15, further comprising a connector connecting the first circuit board and the second circuit board, providing communicability therebetween.

23. The function module as claimed in claim 22, wherein the connector is a slot connector.

24. The function module as claimed in claim 15, further comprising:

a first heat spreader, disposed between the heat dissipation fin and the first heat conduction layer, for uniformly spreading the heat over the first circuit board; and

a second heat spreader, disposed between the heat dissipation fin and the second heat conduction layer, for uniformly spreading the heat over the second circuit board.

25. The function module as claimed in claim 24, wherein both the first heat spreader and the second heat spreader are made of copper, aluminum, metallic composite material, or non-metallic composite material.

26. The function module as claimed in claim 15, wherein both the thermal conductivity of the first heat spreader and the thermal conductivity of the second heat spreader are substantially not less than 100W/m• K.

27. The function module as claimed in claim 15, further comprising:

a first adhesion layer, disposed between the heat dissipation fin and the first heat conduction layer, for combining the heat dissipation fin with the first circuit board; and

a second adhesion layer, disposed between the heat dissipation fin and the second heat conduction layer, for combining the heat dissipation fin with the second circuit board.

28. The function module as claimed in claim 27, wherein both the first adhesion layer and the second adhesion layer comprise one selected from the group consisting of brazing solder, tin solder, thermal interface material, grease and the combination thereof respectively.

29. The function module as claimed in claim 15, further comprising a fan, connected to the heat dissipation fin, for dissipating heat therefrom.

30. The function module as claimed in claim 15, wherein the first heat conduction layer is a power source surface of the first circuit board, and the second heat conduction layer is a power source surface of the second circuit board.